

-100V P-Channel Enhancement Mode MOSFET

Description

The AP35P10D uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

$V_{DS} = -100V$ $I_D = -35A$

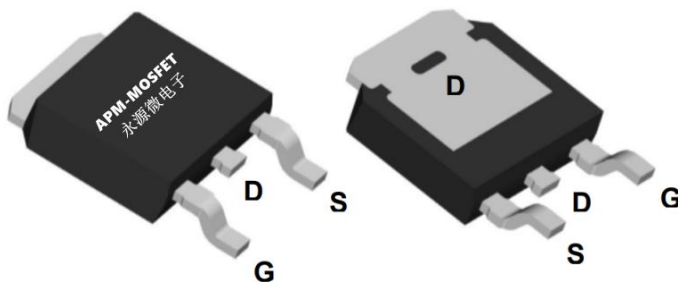
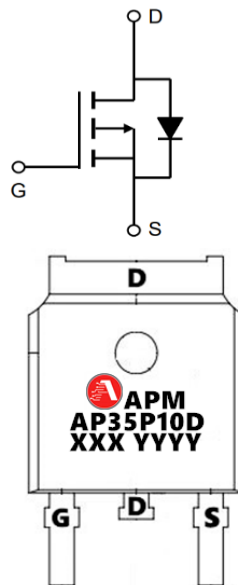
$R_{DS(ON)} < 52m\Omega$ @ $V_{GS}=10V$ (Type: 40m Ω)

Application

Brushless motor

Load switch

Uninterruptible power supply



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP35P10D	TO-252-3L	AP35P10D XXX YYYY	2500

Absolute Maximum Ratings ($T_C=25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-100	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D@T_C=25^{\circ}C$	Continuous Drain Current, V_{GS} @ -10V ¹	-35	A
$I_D@T_C=100^{\circ}C$	Continuous Drain Current, V_{GS} @ -10V ¹	-19	A
IDM	Pulsed Drain Current ²	-110	A
EAS	Single Pulse Avalanche Energy ³	360	mJ
IAS	Avalanche Current	-35	A
$P_D@T_C=25^{\circ}C$	Total Power Dissipation ⁴	119	W
TSTG	Storage Temperature Range	-55 to 150	$^{\circ}C$
T_J	Operating Junction Temperature Range	-55 to 150	$^{\circ}C$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	62.5	$^{\circ}C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	1.35	$^{\circ}C/W$

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Electrical Characteristics (T_J = 25°C, unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V(BR)DSS	Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = -250μA	-100	-	-	V
IGSS	Gate-body Leakage current	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA
IDSS T _J =25°C	Zero Gate Voltage Drain Current	V _{DS} = -100V, V _{GS} = 0V	-	-	-1	μA
IDSS T _J =100°C			-	-	-100	
VGS(th)	Gate-Threshold Voltage	V _{DS} = V _{GS} , I _D = -250μA	-1.2	-1.7	-2.4	V
RDS(on)	Drain-Source on-Resistance ⁴	V _{GS} = -10V, I _D = -20A	-	40	52	mΩ
		V _{GS} = -4.5V, I _D = -10A	-	43	55	
gfs	Forward Transconductance ⁴	V _{DS} = -10V, I _D = -20A	-	44	-	S
Ciss	Input Capacitance	V _{DS} = -50V, V _{GS} = 0V, f = 1MHz	-	5870	-	pF
Coss	Output Capacitance		-	135	-	
Crss	Reverse Transfer Capacitance		-	106	-	
R _g	Gate Resistance	f = 1MHz	-	9.5	-	Ω
Q _g	Total Gate Charge	V _{GS} = -10V, V _{DS} = -50V, I _D = -20A	-	126	-	nC
Q _{gs}	Gate-Source Charge		-	13.9	-	
Q _{gd}	Gate-Drain Charge		-	13	-	
td(on)	Turn-on Delay Time	V _{GS} = -10V, V _{DD} = -50V, R _G = 3 Ω, I _D = -20A	-	15	-	ns
t _r	Rise Time		-	42	-	
td(off)	Turn-off Delay Time		-	68	-	
t _f	Fall Time		-	38	-	
VSD	Diode Forward Voltage ⁴	I _S = -20A, V _{GS} = 0V	-	-	-1.2	V
IS	Continuous Source Current T _C =25°C	-	-	-	-30	A

Note :

- 1、The data tested by surface mounted on a 1 inch 2 FR-4 board with 20Z copper.
- 2、The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3、The EAS data shows Max. rating . The test condition is V_{DD} = -25V, V_{GS} = -10V, L=0.1mH, I_{AS} = -35A
- 4、The power dissipation is limited by 150°C junction temperature
- 5、The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

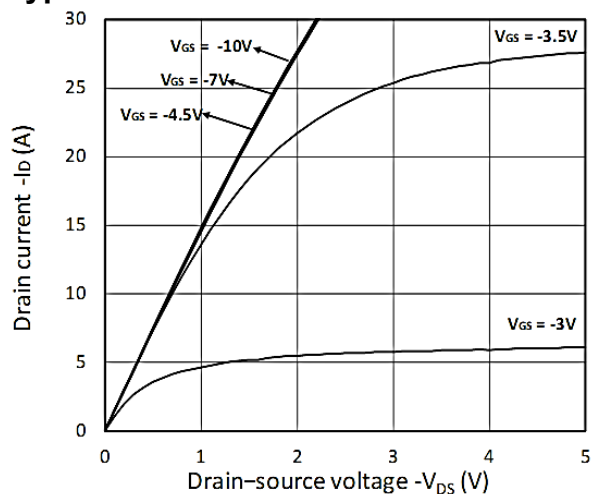


Figure 1. Output Characteristics

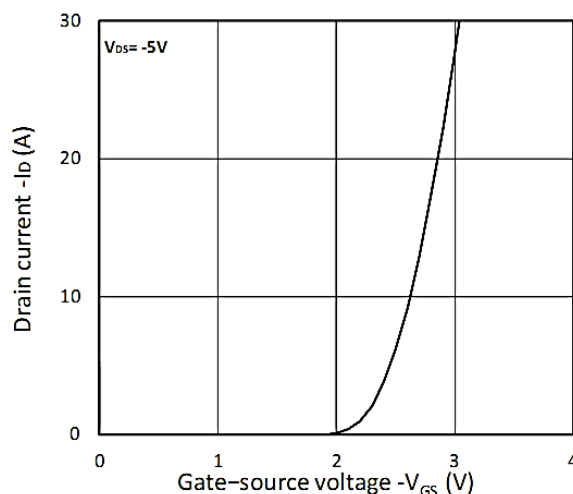


Figure 2. Transfer Characteristics

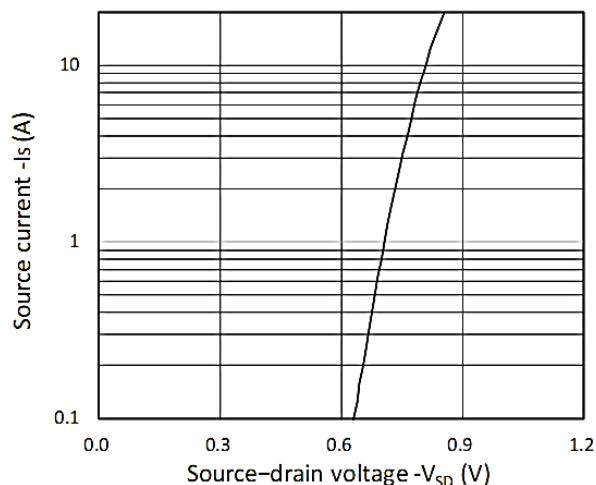


Figure 3. Forward Characteristics of Reverse

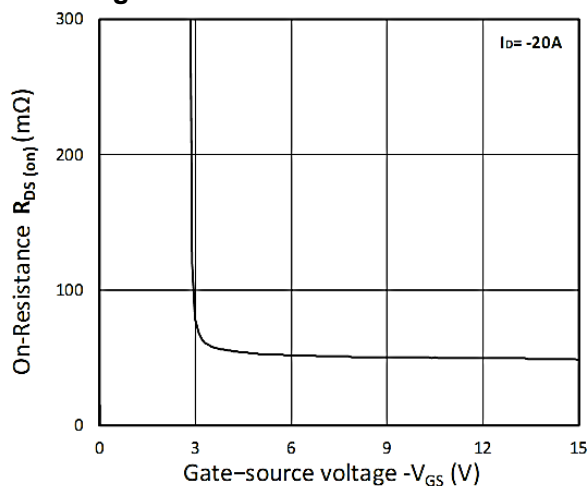


Figure 4. R_DS(ON) vs. V_GS

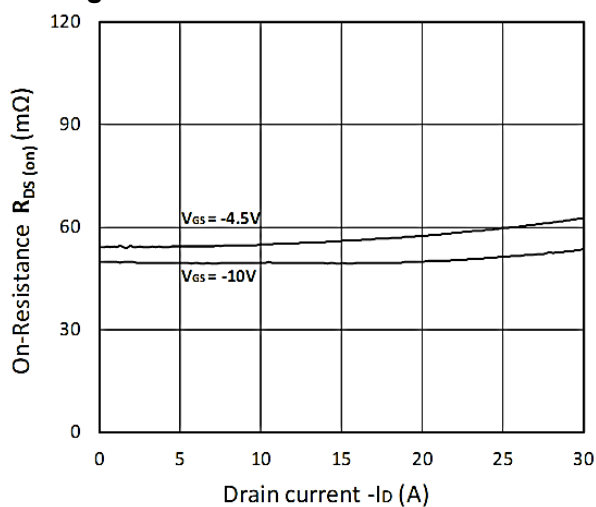


Figure 5. R_DS(ON) vs. I_D

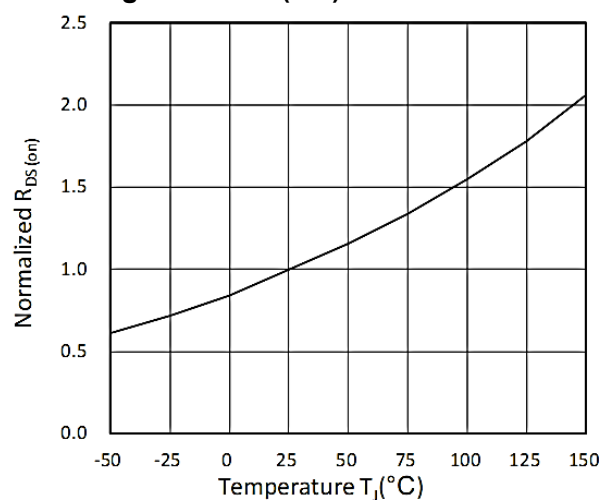


Figure 6. Normalized R_DS(on) vs. Temperature

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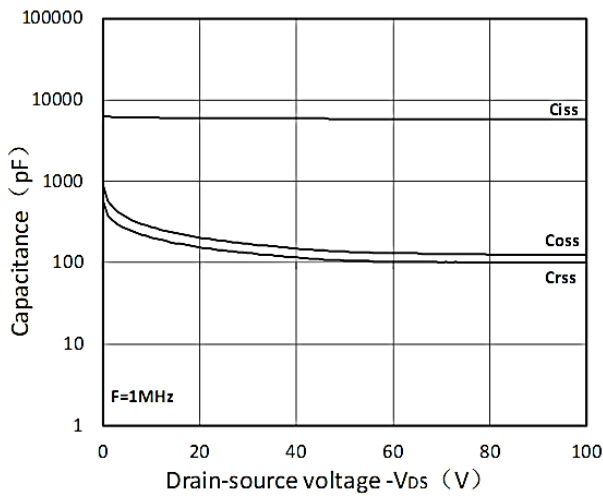


Figure 7. Capacitance Characteristics

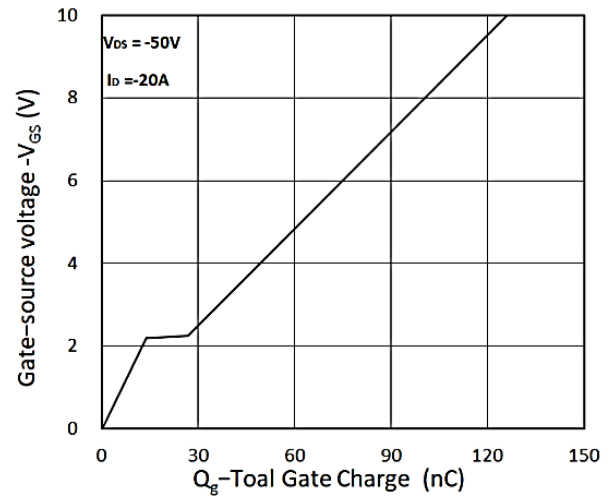


Figure 8. Gate Charge Characteristics

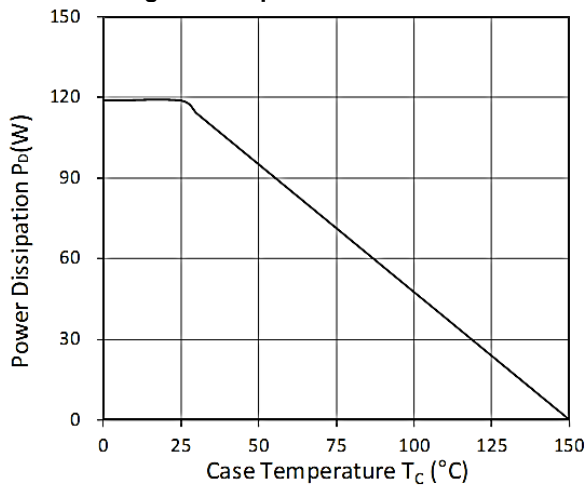


Figure 9. Power Dissipation

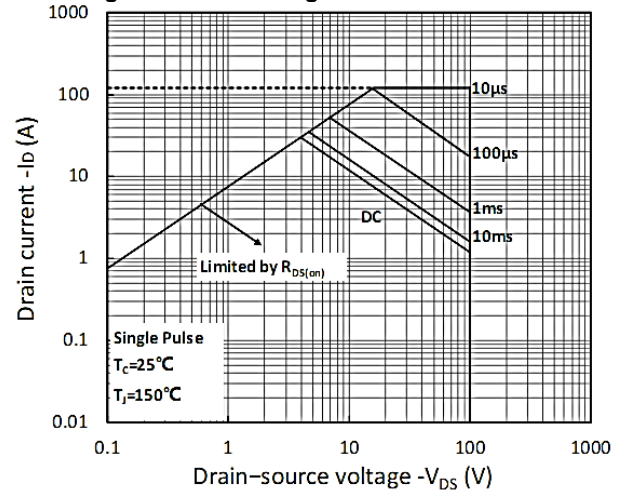


Figure 10. Safe Operating Area

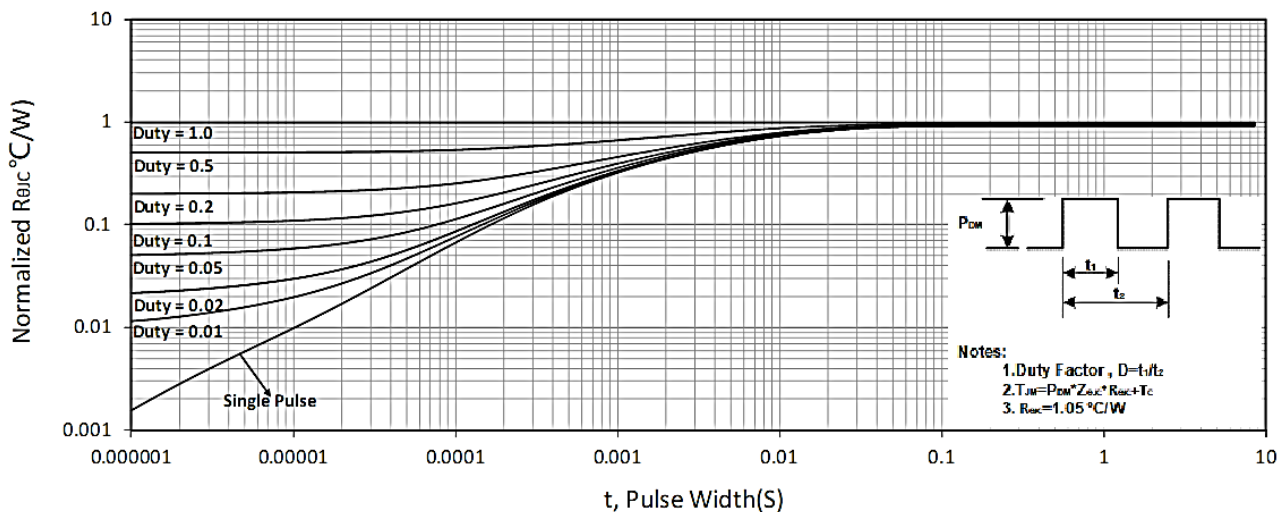
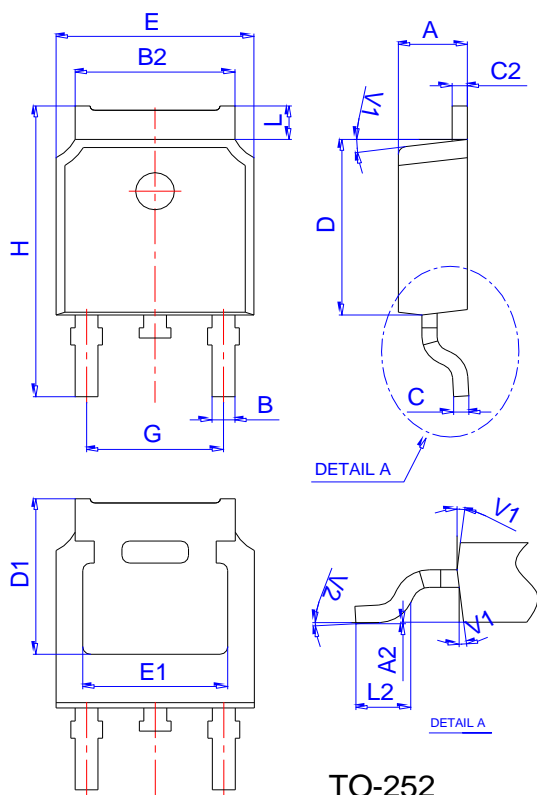


Figure 11. Normalized Maximum Transient Thermal Impedance

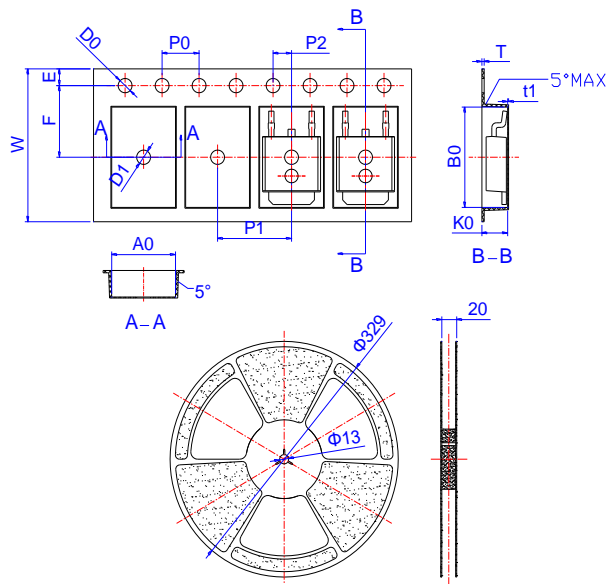
Package Mechanical Data:TO-252-3L



TO-252

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

Reel Specification-TO-252



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
W	15.90	16.00	16.10	0.626	0.630	0.634
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
D0	1.40	1.50	1.60	0.055	0.059	0.063
D1	1.40	1.50	1.60	0.055	0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
A0	6.85	6.90	7.00	0.270	0.271	0.276
B0	10.45	10.50	10.60	0.411	0.413	0.417
K0	2.68	2.78	2.88	0.105	0.109	0.113
T	0.24		0.27	0.009		0.011
t1	0.10			0.004		
10P0	39.80	40.00	40.20	1.567	1.575	1.583

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Edition	Date	Change
REV1.0	2023/4/13	Initial release
REV1.1	2023/11/21	Reduce RDS

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